Devcon Epoxy Plus[™] 25

Epoxy; Epoxide

Devcon

Message:

Rubber-toughened, high viscosity, structural adhesive with superior impact, peel and fatigue resistance. Intended Use: Bonds metals, thermoset plastics and structural parts. Product Features: Non-shrinking High dielectric strength Excellent durability and flexibility

General Information	
Features	Impact resistance, high
	Good flexibility
	Fatigue resistance
	Durability
	Low shrinkage
	Viscosity, High
Uses	Bonding
	Adhesive

Appearance	Grey		
Physical	Nominal Value	Unit	Test Method
Specific Volume	0.838	cm³/g	
Solid content-by Volume	100	%	
Impact Resistance	21.0	kJ/m²	
Service Temperature	-40 - 93	°C	
Work Time	25.0	min	
Tensile Shear Adhesion	19.0	MPa	ASTM D1002
Density ¹	1.14	g/cm³	
Hardness	Nominal Value	Unit	Test Method
Durometer Hardness (Shore D)	74		ASTM D2240
Mechanical	Nominal Value	Unit	
Tensile Elongation (Break)	20	%	
Electrical	Nominal Value	Unit	Test Method
Dielectric Strength	22	kV/mm	ASTM D149
Thermoset	Nominal Value	Unit	Test Method
Thermoset Components			

Component a	Mixing ratio by capacity: 1.0		
	Mixing ratio by weight: 43		
Component B	Mixing ratio by capacity: 1.0		
Thermoset Mix Viscosity	70000	сР	
Additional Information	Nominal Value	Unit	Test Method
Cured 7 days @ 75°F			
Uncured Properties	Nominal Value	Unit	Test Method
Curing Time	30	hr	
NOTE			
1.	Mixed		

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